

ISOPLUS™ – Isolated Discrete Power Semiconductors

Objectives

This document outlines the specific product features of the ISOPLUS™ power semiconductor family. **Figure 1** displays some of the family's packages.

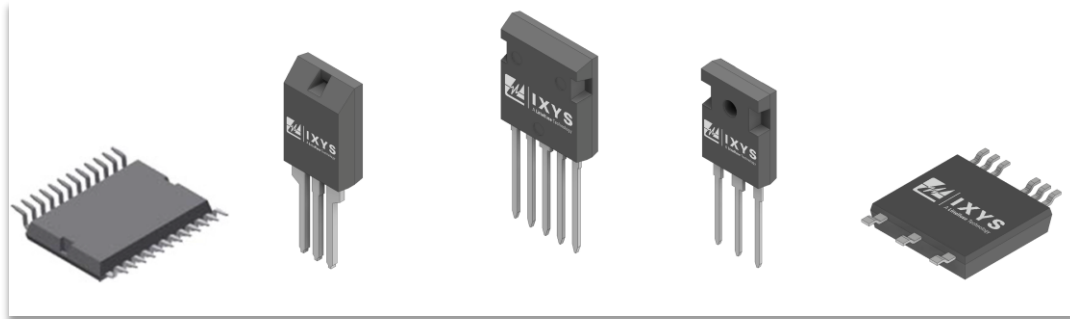


Figure 1. ISOPLUS™ Packages SMPD-DIL, TO-220, TO-247, I4-Pac and SMPD-B

Applications

- Industrial drives
- EV-charging
- White Goods
- Power Supplies
- Renewable energies

Target Audience

This document is intended for all power electronic developers confronted with hardware design and the challenge to build reliable systems with a focus on reasonable effort in component choice, layout, and thermal management.

Contact Information

For more information on this topic, contact the Littelfuse Power Semiconductor team of product and applications experts:

- North America – NA_PowerSemi_Tech@Littelfuse.com
- Central & South America – CSA_PowerSemi_Tech@Littelfuse.com
- Europe, Middle East, & Africa – EMEA_PowerSemi_Tech@Littelfuse.com
- Asia, Australia, & Pacific Islands – APAC_PowerSemi_Tech@Littelfuse.com

Table of Contents

1. Introduction	3
2. Power Device	3
3. Mechanical Construction	3
4. Comparing the Thermal Situation	4
5. Assembly Benefits	5
6. Available Packages	6

List of Figures

Figure 1. ISOPLUS™ Packages SMPD-DIL, TO-220, TO-247, I4-Pac and SMPD-B.....	1
Figure 2. Cross-section of an ISOPLUS™ Device.....	3
Figure 3. Thermal Model of an Isolated Package using Thermal Grease.....	4
Figure 4. Thermal Model of a Non-insulated Package using a Silicone Pad.....	4
Figure 5. Thermal Model of a Non-insulated Package using a Ceramic Platelet and Thermal Grease.....	5
Figure 6. Comparing Electrical Performance of ISOPLUS™ 274 and PLUS247™ Devices	5

List of Tables

Table 1. The ISOPLUS Family Members	6
---	---

1. Introduction

When using power semiconductors, there is usually a need to electrically isolate the devices from the heatsink, which could also be the equipment’s chassis or housing. The main reasons for this are safety, the necessity to reduce electromagnetic interference by reducing stray capacitance between the chip and ground, and the desire to mount several devices onto the same heatsink.

Major penalties involve increased thermal resistances, complex assembly, and difficulty in testing of the insulation quality to meet different global safety standards. The most common method is to use an insulating material, sandwiched between the semiconductor device and the heatsink. Inherently, this increases the thermal resistance case-to-heatsink R_{thcs} .

Implementing discrete power semiconductors by adapting technologies from power modules led to the development of the ISOPLUS™ family. Here, a combination of insulating carriers with copper lead-frames and bond-wire interconnection enables an internal construction that achieves high insulation strength without sacrificing thermal performance.

This application note describes the major properties for the ISOPLUS™ Family.

2. Power Device

The ISOPLUS™ family today consists of a variety of different packages that all feature the same approach regarding internal construction and insulation. Being a power semiconductor platform, ISOPLUS™ family members are available in a wide range of technologies, topologies, and voltage classes.

3. Mechanical Construction

The key engineering achievement is the extension of the common copper lead frame by a copper-ceramic-copper laminate called Direct Copper Bonding or DCB. The ceramic itself can withstand an insulation voltage higher than 6 kV but for the ISOPLUS™-family, it is rated to 2.5 kV with respect to the external creepage and clearance distances of the package. The semiconductors are soldered to the structured DCB-frontside while the opposite side of the substrate is used for direct mounting to a heatsink. Interconnections of the chips is done using bond-wires. As an example, the cross section of the ISOPLUS™ SMPD package is displayed in **Figure 2**.

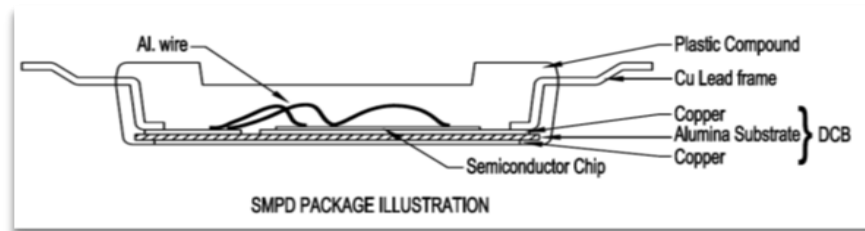


Figure 2. Cross-section of an ISOPLUS™ Device

The total number of layers from the heat source to the heatsink has been minimized to only one solder layer, the DCB ceramic and an external thermal grease. This results in a very low thermal resistance between chip and heatsink. Soldering the chip onto the DCB substrate that includes an insulator is a well-proven method for chip attachment and widely used in power semiconductor modules.

A common feature of all ISOPLUS™ devices is the hole-free package. In addition to the improvements in thermal performance, the area consumed by the mounting hole can now be utilized too.

4. Comparing the Thermal Situation

In contrast to traditional lead-frame-based packages with electrically active backsides, all members of the ISOPLUS™-family can be mounted to a heat sink by simply adding a high-performance Thermal Interface Material (TIM). Though these materials are available qualified as electrically non-conductive, this may not be misinterpreted as offering a qualified insulation strength. Applied to achieve a thin bond line between the power electronic component and the heat sink, a direct metal-to-metal contact cannot be excluded. From a thermal transfer point of view, maximizing this contact is beneficial as direct metal contacts provide the lowest possible thermal resistance. With non-insulated devices, this connection could lead to unwanted, potentially hazardous effects and needs to be prevented. As an isolator is needed between an active part and the heat sink, the chain of thermal resistances involved is unnecessarily prolonged.

Inherently, the thermal transfer capability of the connection is reduced.

Figure 3 sketches the setup as well as the chain of thermal resistances using an ISOPLUS™ device in combination with grease as thermal interface material.

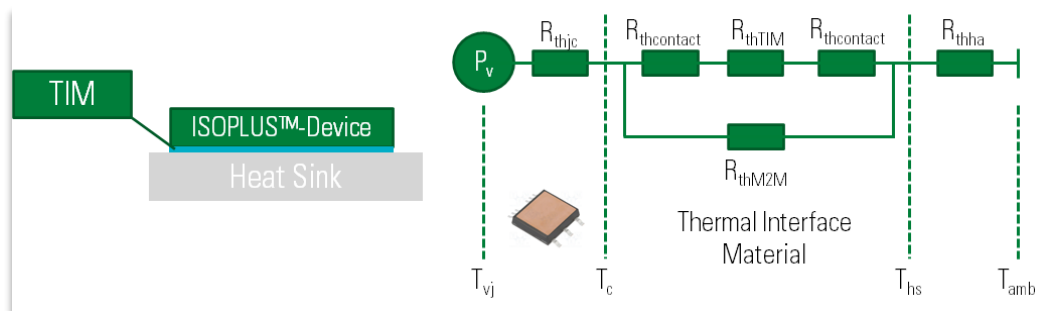


Figure 3. Thermal Model of an Isolated Package using Thermal Grease

The thermal resistance from junction to case R_{thjc} is defined by the solid construction of the power semiconductor. The path from the device's case to the heat sink's surface R_{thch} depends on the thermal interface in use. It's bulk resistance R_{thTIM} is typically given in the datasheet. Equally important is the material's capability to contact the surfaces to reduce the contact resistances $R_{thcontact}$ and allow a direct metal-to-metal path R_{thM2M} .

In comparison, a material with a guaranteed insulation strength changes the setup as inherently the metal-to-metal contact is eliminated. **Figure 4** depicts the difference, assuming a soft insulation layer like a silicone pad.

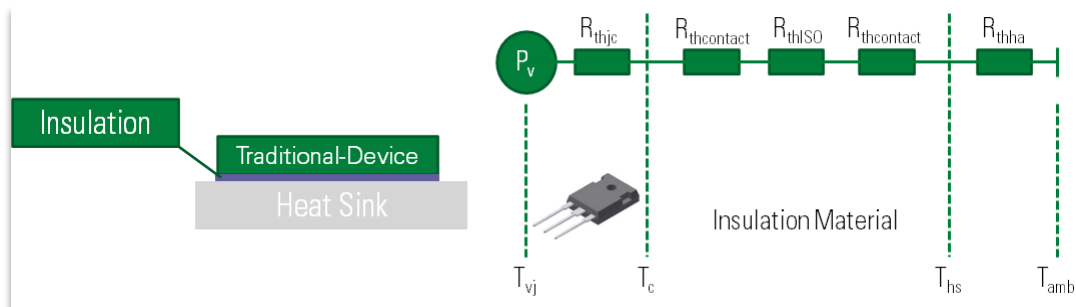


Figure 4. Thermal Model of a Non-insulated Package using a Silicone Pad

Without the metal-to-metal contact, a highly efficient part of the thermal chain is missing. Additionally, the contact resistance as well as the material's bulk resistance are higher than those of high-performance thermal greases, leading to lower thermal performance of the structure.

Replacing the soft material with a higher performance version like ceramic sheets further worsens the situation. These hard materials do not offer low contact resistances. A thermal grease needs to be used on both sides of such platelets, unnecessarily increasing the thermal resistance further, as seen in **Figure 5**.

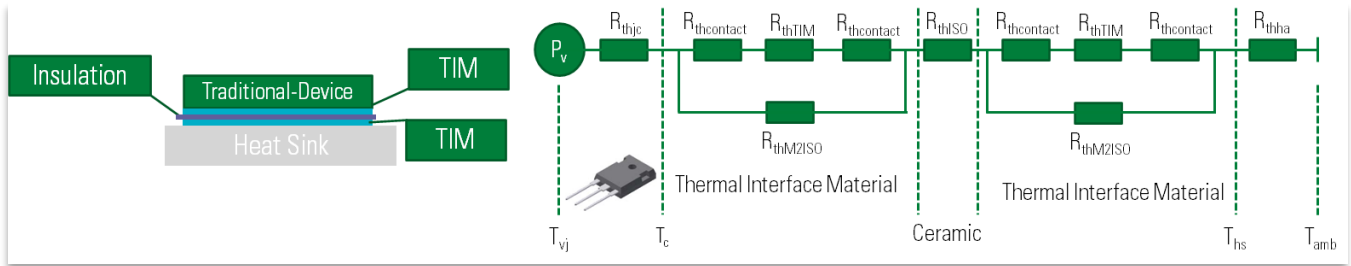


Figure 5. Thermal Model of a Non-insulated Package using a Ceramic Platelet and Thermal Grease

The improved thermal performance turns into higher electrical performance, as summarized in the diagram given in **Figure 6**.

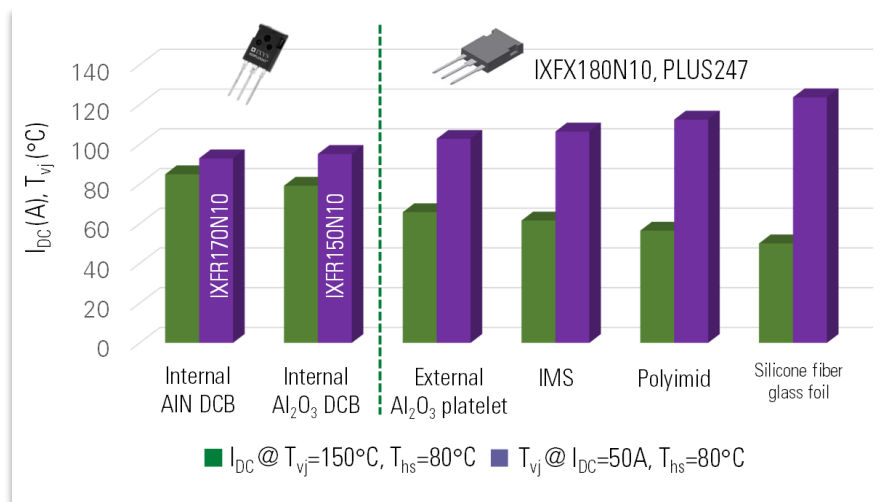


Figure 6. Comparing Electrical Performance of ISOPLUS™ 274 and PLUS247™ Devices

The PLUS247™ package is derived from the standard TO-247 and shares the same mechanical construction. To allow larger dies inside the package, no mounting hole is present in this package. Though the device used for this comparison holds the larger die inside, the DC-current achieved at maximum junction temperature is lower, compared to a smaller die in the ISOPLUS-setup. Vice versa, at the same chip current, the chip temperature is lower within the ISOPLUS-device, leading to a gain in device lifetime.

5. Assembly Benefits

Traditional devices with an active backside require insulation as described in case all devices involved are mounted on the same heat sink. Instead, another approach consists of designs that group components with the same collector-potential to a common heat sink. This allows for improvement of the thermal situation but leads to other drawbacks. In a classical sixpack, this requires having four dedicated heat sinks that in turn need to remain insulated from each other. In more complex structures, this leads to an unnecessary number of heat sinks and inconvenient assembly processes.

Because of the insulated construction, multiple ISOPLUS™-devices can be mounted on a common heat sink. Correlating mounting suggestions can be found in the application note *Mounting and Cooling Solutions for SMPD Packages*.

6. Available Packages

Since the introduction of the ISOPLUS™ family back in 1998, additional packages have been added, as pictured in **Table 1**.

Table 1. The ISOPLUS Family Members

Overview on the ISOPLUS-Family		
		
ISOPLUS220™	ISOPLUS247™	ISOPLUS264™
		
ISOPLUS I4-PAC™	ISOPLUS I4-PAC™	ISOPLUS I4-PAC™
		
ISOPLUS264™	ISOPLUS-DIL™	ISOPLUS-DIL™
		
ISOPLUS-SMPD™-B	ISOPLUS-SMPD™-X	ISOPLUS-SMPD™-Y

In each package, a variety of technologies, topologies, and voltage classes is available. The most recent information can be found in the Power Semiconductor Product Catalog. The file can be downloaded from the [Technical Resources](#) page on the Littelfuse website.

Revision	Date	Major work done
1.0	2001	IXYS AN0025 on the ISOPLUS™
21.09a	2021	Reworked and updated

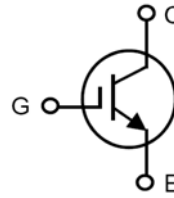
For additional information please visit www.Littelfuse.com/powersemi

Disclaimer Notice - This document is provided by Littelfuse, Inc. ("Littelfuse") for informational and guideline purposes only. Littelfuse assumes no liability for errors or omissions in this document or for any of the information contained herein. Information is provided on an "as is" and "with all faults" basis for evaluation purposes only. Applications described are for illustrative purposes only and Littelfuse makes no representation that such applications will be suitable for the customer's specific use without further testing or modification. Littelfuse expressly disclaims all warranties, whether express, implied or statutory, including but not limited to the implied warranties of merchantability and fitness for a particular purpose, and non-infringement. It is the customer's sole responsibility to determine suitability for a particular system or use based on their own performance criteria, conditions, specific application, compatibility with other components, and environmental conditions. Customers must independently provide appropriate design and operating safeguards to minimize any risks associated with their applications and products.

Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, automotive, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly forth in applicable Littelfuse product documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation.

Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics

For Capacitor Discharge Applications

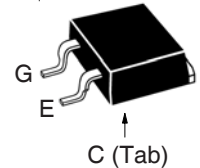


$$V_{CES} = 2500V$$

$$I_{C110} = 12A$$

$$V_{CE(sat)} \leq 3.1V$$

TO-263HV



G = Gate C = Collector
E = Emitter Tab = Collector

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_J = 25^\circ C$ to $150^\circ C$	2500	V
V_{GGR}	$T_J = 25^\circ C$ to $150^\circ C$, $R_{GE} = 1M\Omega$	2500	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ C$	30	A
I_{C110}	$T_C = 110^\circ C$	12	A
I_{CM}	$T_C = 25^\circ C$, $V_{GE} = 19V$, 1ms 10ms	105	A
		55	A
SSOA	$V_{GE} = 15V$, $T_{VJ} = 125^\circ C$, $R_G = 20\Omega$	$I_{CM} = 60$	A
(RBSOA)	Clamped Inductive Load	1500	V
P_C	$T_C = 25^\circ C$	150	W
T_J		-55 ... +150	$^\circ C$
T_{JM}		150	$^\circ C$
T_{stg}		-55 ... +150	$^\circ C$
T_L	Maximum Lead Temperature for Soldering	300	$^\circ C$
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	$^\circ C$
V_{ISOL}	50/60Hz, 1 Minute	4000	V~
Weight		2.3	g

Features

- International Standard Package
- High Voltage Package
- Electrically Isolated Tab
- High Peak Current Capability
- Low Saturation Voltage
- Molding Epoxies Meet UL 94 V-0 Flammability Classification

Advantages

- High Power Density
- Easy to Mount

Applications

- Capacitor Discharge
- Pulsar Circuits

Symbol	Test Conditions ($T_J = 25^\circ C$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{CES}	$I_C = 250\mu A$, $V_{GE} = 0V$	2500		V
$V_{GE(th)}$	$I_C = 250\mu A$, $V_{CE} = V_{GE}$	3.0		5.0 V
I_{CES}	$V_{CE} = 0.8 \cdot V_{CES}$, $V_{GE} = 0V$ $T_J = 125^\circ C$			25 μA 750 μA
I_{GES}	$V_{CE} = 0V$, $V_{GE} = \pm 20V$			± 100 nA
$V_{CE(sat)}$	$I_C = 20A$, $V_{GE} = 15V$, Note 1			3.1 V

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$I_C = 20\text{A}$, $V_{CE} = 10\text{V}$, Note 1	8	13	S
$I_{C(ON)}$	$V_{GE} = 20\text{V}$, $V_{CE} = 15\text{V}$, Note 1		190	A
C_{ies}	$V_{CE} = 15\text{V}$, $V_{GE} = 25\text{V}$, $f = 1\text{MHz}$		1190	pF
C_{oes}			53	pF
C_{res}			18	pF
Q_g	$I_C = 20\text{A}$, $V_{GE} = 15\text{V}$, $V_{CE} = 1000\text{V}$		53	nC
Q_{ge}			8	nC
Q_{gc}			22	nC
$t_{d(on)}$	Resistive Switching Times $I_C = 40\text{A}$, $V_{GE} = 15\text{V}$, Note 1 $V_{CE} = 1250\text{V}$, $R_G = 10\Omega$		57	ns
t_r			160	ns
$t_{d(off)}$			136	ns
t_f			930	ns
R_{thJC}				0.83 $^\circ\text{C/W}$

Note 1. Pulse test, $t < 300\mu\text{s}$, duty cycle, $d < 2\%$.

TO-263HV Outline

CREEPAGE DISTANCE		
DESCRIPTION	SYMBOL	MIN DISTANCE
LEAD TO LEAD AIR CLEARANCE	e2	0.163 [4.15mm]
LEAD TO LEAD Pkg SURFACE CREEPAGE	e2	0.165 [4.20mm]
LEAD TO BOTTOM DRAIN CREEPAGE	A2+D2	0.177 [4.50mm]

SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.170	.185	4.30	4.70
A1	.000	.008	0.00	0.20
A2	.091	.098	2.30	2.50
b	.028	.035	0.70	0.90
b2	.046	.054	1.18	1.38
C	.018	.024	0.45	0.60
C2	.049	.055	1.25	1.40
D	.354	.370	9.00	9.40
D1	.311	.327	7.90	8.30
D2	.083	.098	2.10	2.50
E	.386	.402	9.80	10.20
E1	.307	.323	7.80	8.20
e1	.200	BSC	5.08	BSC
(e2)	.163	.174	4.13	4.43
H	.591	.614	15.00	15.60
L	.079	.102	2.00	2.60
L1	.039	.055	1.00	1.40
L3	.010	BSC	0.254	BSC
(L4)	.071	.087	1.80	2.20

NOTE:

1. These dimensions do not include mold protrusion.
2. () is reference dimension only.
3. Metal finish – Matte pure tin plating except trim area.
4. Pin call out: 1- Gate; 2 - Emitter; 3 - Collector

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

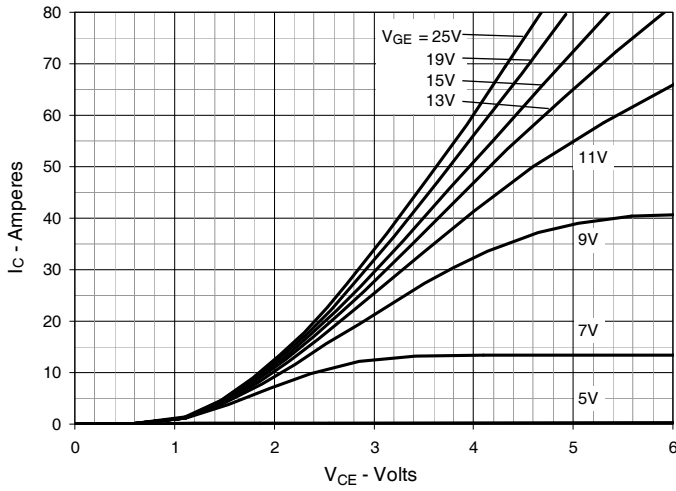


Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

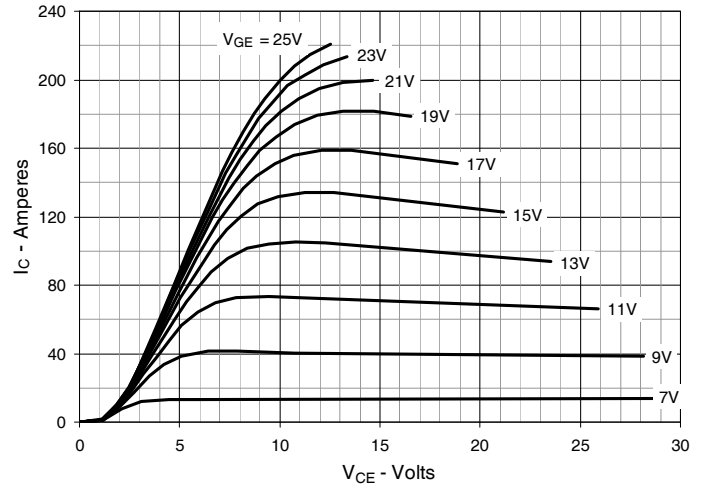


Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$

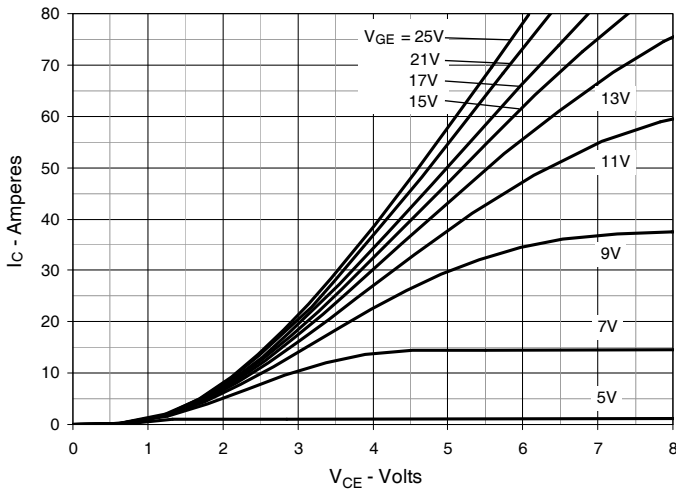


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

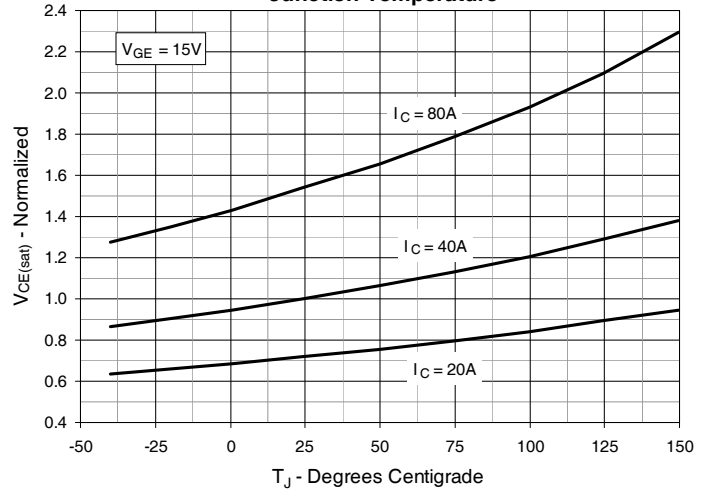


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

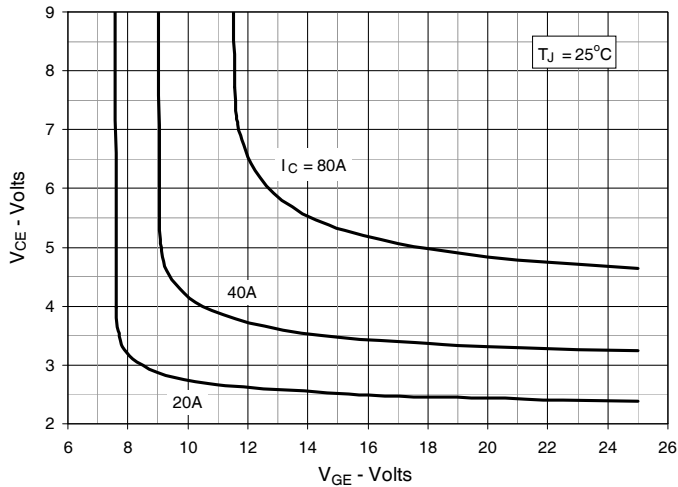


Fig. 6. Input Admittance

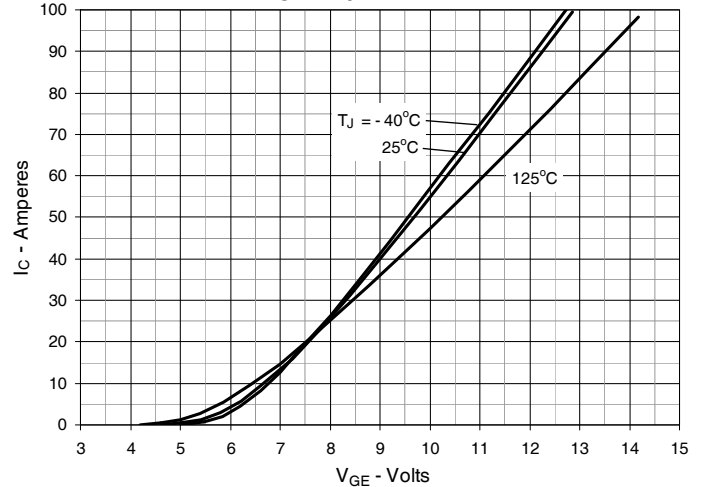


Fig. 7. Transconductance

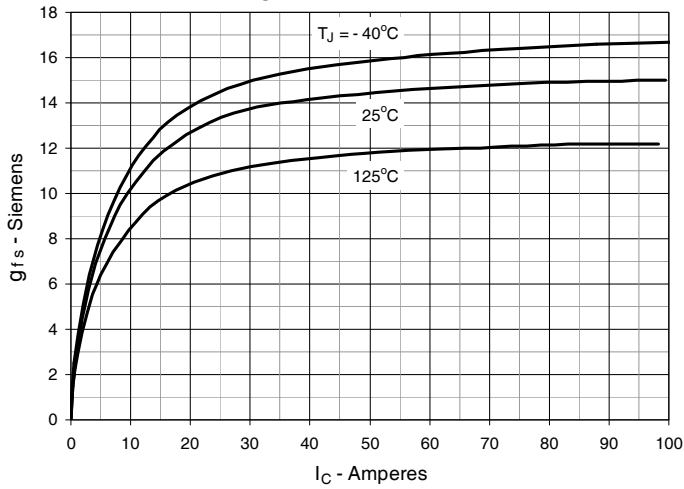


Fig. 8. Gate Charge

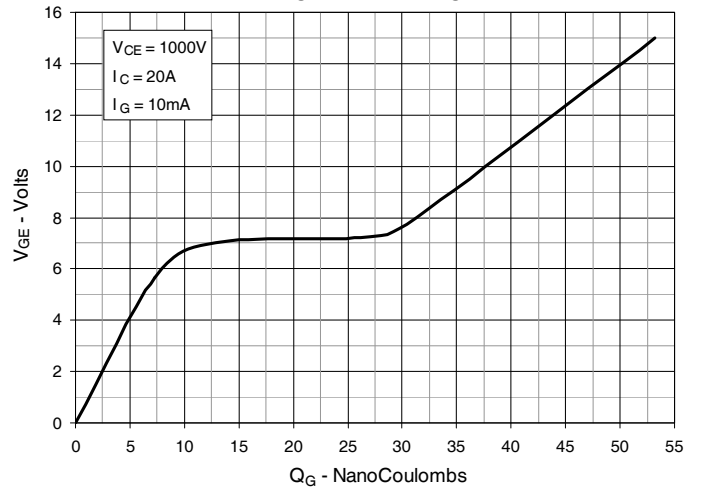


Fig. 9. Reverse-Bias Safe Operating Area

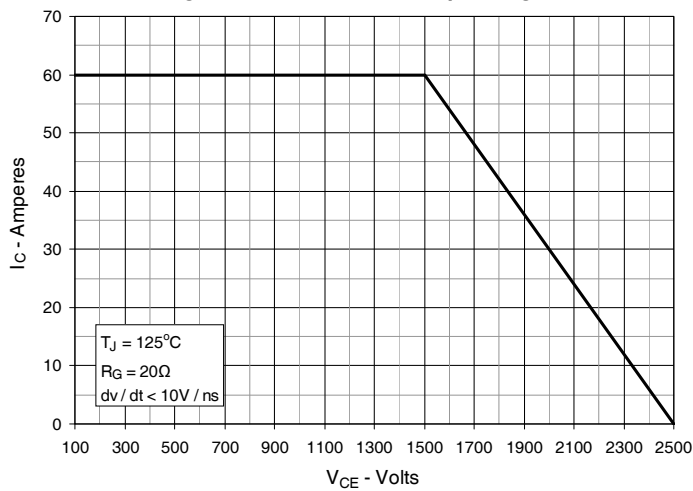


Fig. 10. Capacitance

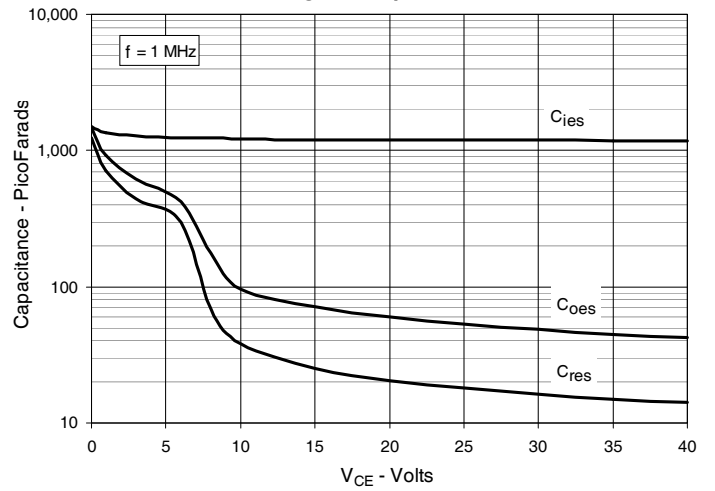


Fig. 11. Maximum Transient Thermal Impedance

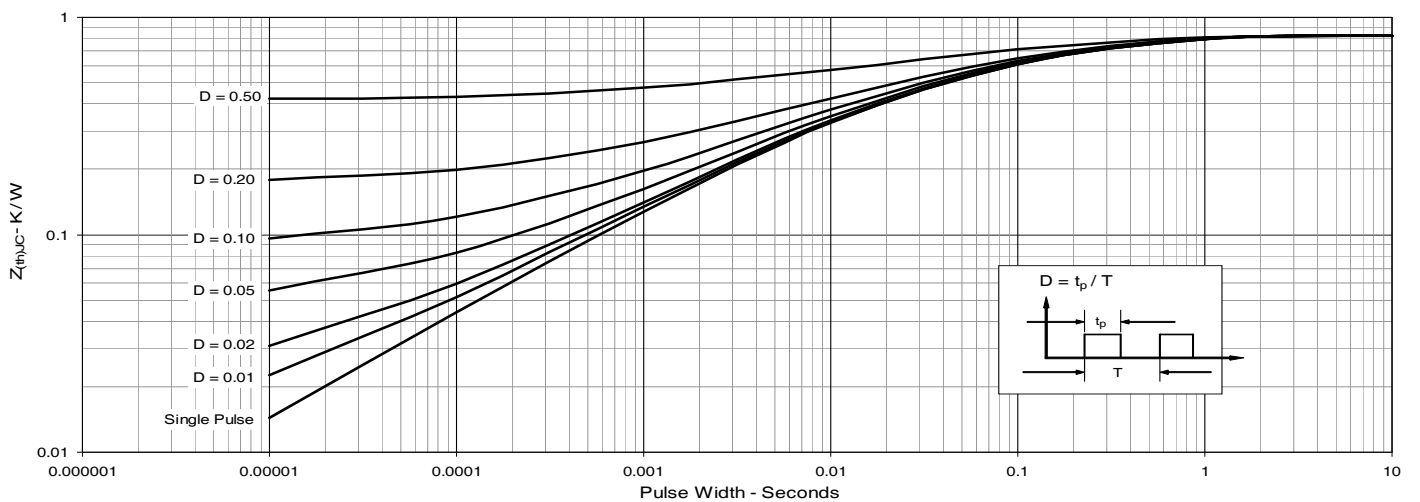


Fig. 12. Resistive Turn-on Rise Time vs. Junction Temperature

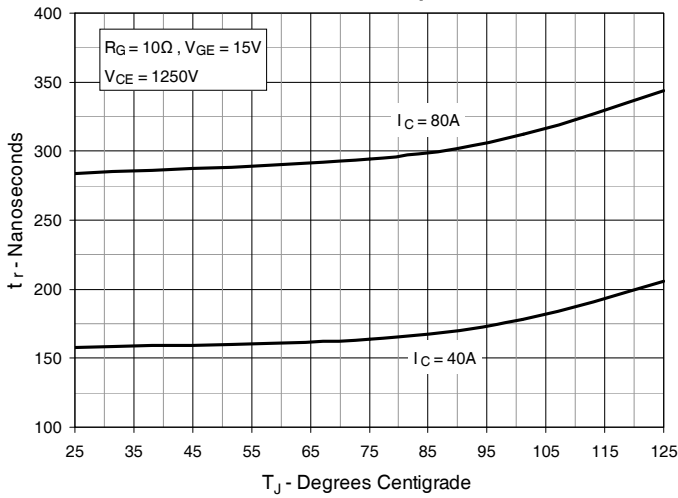


Fig. 13. Resistive Turn-on Rise Time vs. Collector Current

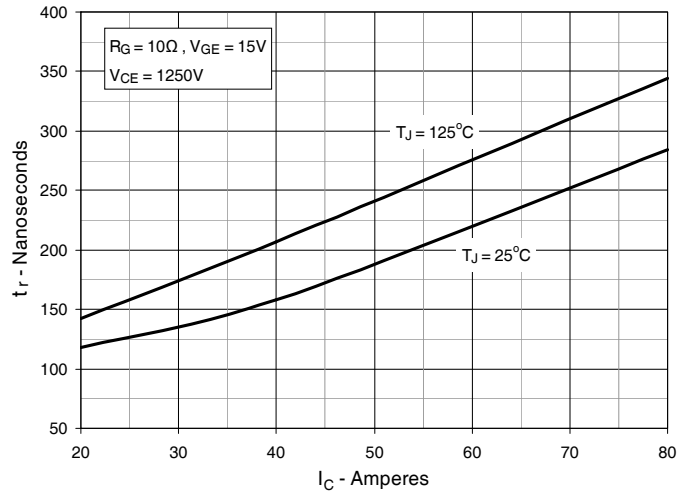


Fig. 14. Resistive Turn-on Switching Times vs. Gate Resistance

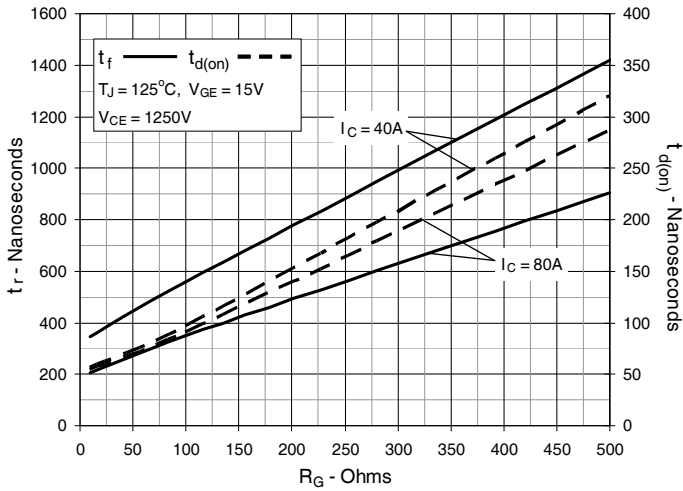


Fig. 15. Resistive Turn-off Switching Times vs. Junction Temperature

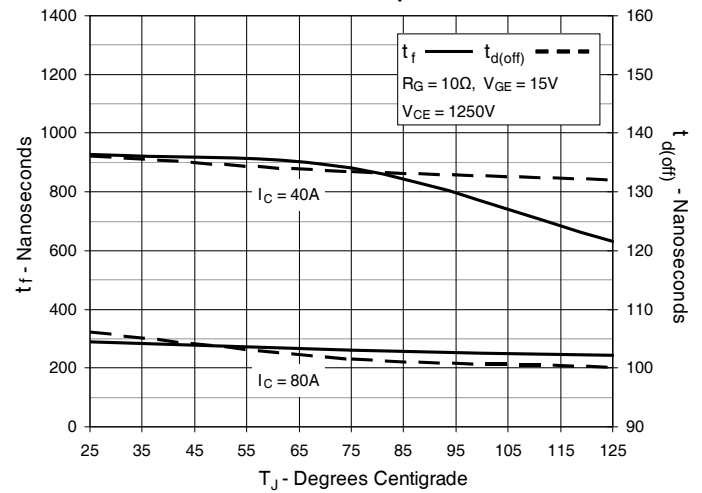


Fig. 16. Resistive Turn-off Switching Times vs. Collector Current

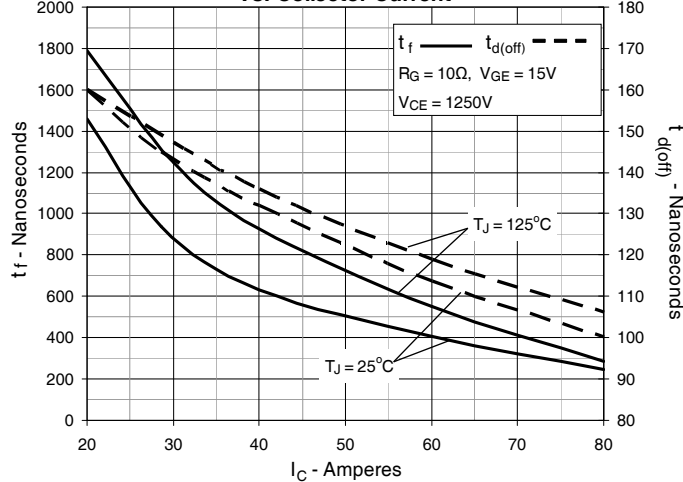
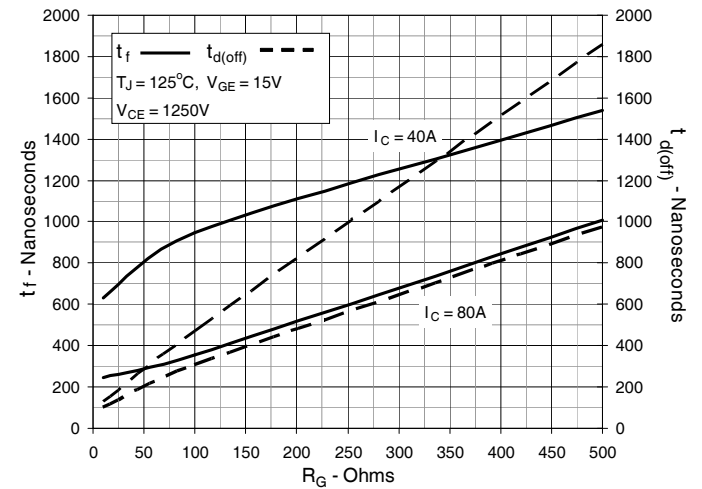


Fig. 17. Resistive Turn-off Switching Times vs. Gate Resistance





Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

Forward-Biased, Reverse-Biased, and Short-Circuit Safe Operating Area of MOSFETs and IGBTs



Objectives

This document explains the operating conditions that a power semiconductor is supposed to work in without being damaged. Focus is set on the *Forward-Biased Safe Operating Area (FBSOA)*, the *Reverse Biased, Safe Operating Area (RBSOA)* and the *Short-Circuit Safe Operating Area (SCSOA)*.

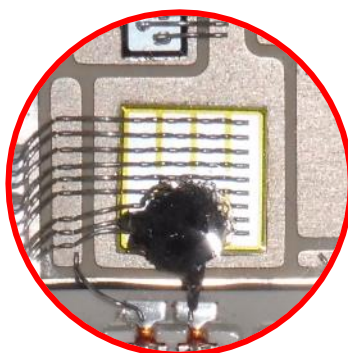


Figure 1. To be prevented – an IGBT destroyed by RBSOA-exceedance

Applications

The information compiled in this document is relevant for the power semiconductor itself and thus for all its applications.

Target Audience

This document is intended for all developers, design- and test-engineers involved in building power semiconductor applications.

Contact Information

For more information on the topic of safely operating power devices, contact the Littelfuse Power Semiconductor team of product and applications experts:

- PowerSemiSupport@Littelfuse.com

Table of Contents

1. Safe Operating Area (SOA), also called Forward-Bias Safe Operating Area (FBSOA).....	4
2. Reverse Biased Safe Operating Area (RBSOA)	5
3. Short-Circuit Safe Operating Area (SCSOA).....	6
4. Resulting challenges for the designer	6
5. Conclusion.....	8

List of Figures

Figure 1. To be prevented – an IGBT destroyed by RBSOA-exceedance	1
Figure 2. SOA Diagram for the IXTX46N50L	4
Figure 3. Voltage and current waveforms during a turn-off event	5
Figure 4. RBSOA-shape, limited by maximum current and breakdown voltage	5
Figure 5. SCSOA information taken from the MDMA280UB1600PTED datasheet.....	6
Figure 6. RBSOA, SCSOA, and the undefined region in between.....	6
Figure 7. Measurement results from a destructive turn-off event.....	7
Figure 8. Locating the point of turn-off	7
Figure 9. Properly turned off overcurrent or short-circuit event.....	8

Introduction

Power semiconductors like IGBTs, GTOs, thyristors, diodes, or bipolar junction transistors (BJT) have been developed into robust and reliable devices which can by now handle power levels into the MW-range and even beyond.

Despite these developments, they all have physical limitations which need to be known and respected to prevent damage to these components and the system they are mounted in. Depending on the instantaneous mode of operation, different conditions are described by a varying set of parameters, often referred to as operating area.

1. Safe Operating Area (SOA), also called Forward-Bias Safe Operating Area (FBSOA)

When a power semiconductor like an IGBT is used to conduct current in the predestined direction, the physical limits of the device to be considered include:

- the maximum collector current I_C ,
- the saturation voltage V_{CEsat} across the device,
- the power generated by the product $I_C \cdot V_{CEsat}$, and
- the maximum junction temperature T_{VJ} allowed.

In cases where the power semiconductor is a MOSFET, dedicated to be operated in linear mode, the current can be influenced by tuning the gate-source-voltage accordingly. As a consequence, the drain-source-voltage V_{DS} of the devices changes which in turn impacts the losses. The device must dissipate these losses and the thermal impedance of the device poses the limits here.

For these operating conditions, the FBSOA-diagram features the forward voltage, the current and limits imposed by thermal development. Looking at Figure 2, it becomes obvious that growing losses can only be tolerated for shorter periods of time.

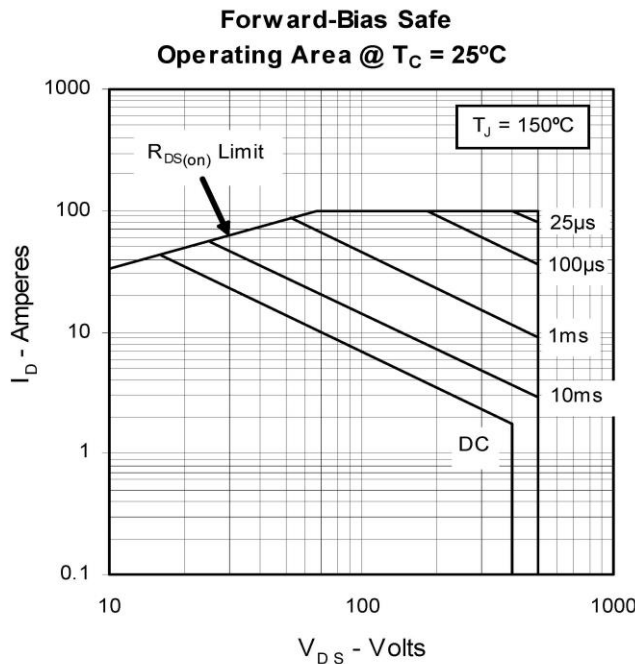


Figure 2. SOA Diagram for the IXTX46N50L

Any combination of forward voltage and current that is found below the correlating lines within the diagram is a legal point of operation as long as the junction temperature remains below the maximum limit and the duration of the loading is properly chosen. De-rating must be considered if the case temperature is different from the 25°C the diagram in Figure 2 refers to.

2. Reverse Biased Safe Operating Area (RBSOA)

Power semiconductors like IGBTs or MOSFETs can turn off a current rather quickly but not at infinite speed. As the switching procedure does take some time, transient phenomena happen that need to be considered.

During this short period, when the device turns from conducting into blocking mode, the Reverse Biased Safe Operating Area needs to be respected at any time.

The limits are given by the current which is turned off and the voltage that appears across the device. The plot in Figure 3 schematically displays a turn-off event in detail.

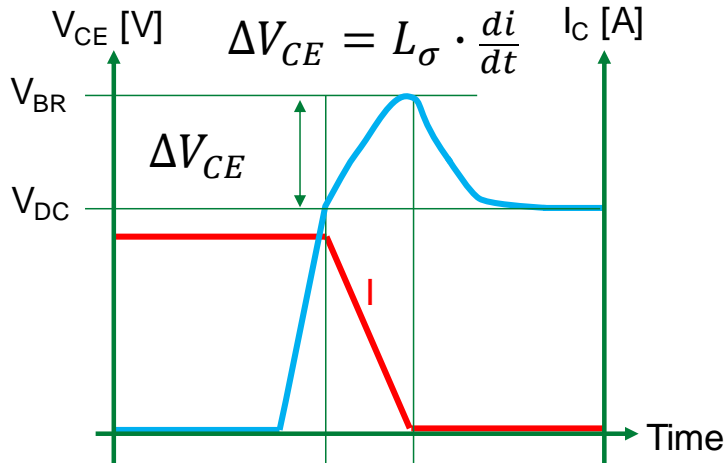


Figure 3. Voltage and current waveforms during a turn-off event

In the graph, it can clearly be seen that the voltage across the device first reaches the DC-link’s voltage level before the current starts declining. Because of the current change rate di/dt and the inherently contained stray inductances L_σ , the voltage spike ΔV_{CE} is added on top of the DC-link voltage. If this spike exceeds the device’s breakdown voltage V_{BR} – even for a very short period of time – the device will be destroyed.

The square-shaped Reverse Biased Safe Operating Area therefore is given by maximum current $I_{C,max}$ and the breakdown voltage V_{BR} , as depicted in Figure 4. Here too, the junction temperature poses a further limit.

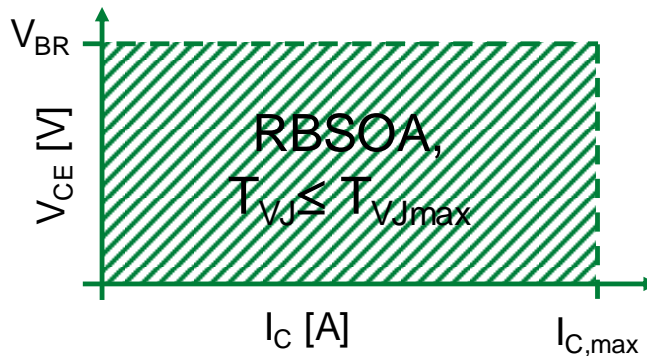


Figure 4. RBSOA-shape, limited by maximum current and breakdown voltage

3. Short-Circuit Safe Operating Area (SCSOA)

Devices that feature desaturation, like most IGBTs, can withstand short-circuit events for a distinct duration. Corresponding datasheets highlight this information as Short Circuit Safe Operating Area or SCSOA. Such a datasheet’s excerpt is given in Figure 5.

SCSOA	<i>short circuit safe operating area</i>	$V_{CEK} = 1200\text{ V}$				
t_{sc}	<i>short circuit duration</i>	$V_{CE} = 720\text{ V}; V_{GE} = \pm 15$	$T_{VJ} = 125^{\circ}\text{C}$		10	μs
I_{sc}	<i>short circuit current</i>	$R_G = 6.8\ \Omega$; non-repetitive		450		A

Figure 5. SCSOA information taken from the MDMA280UB1600PTED datasheet

The short circuit condition demands that the IGBT goes into desaturation. In this mode, no further charge carriers remain available which also limits the current. Typically, IGBTs limit the short-circuit current to about three to four times their rated current. In the example in Figure 5, the 160 A-device is expected to limit the short circuit current to 450 A. This situation is tolerable for 10 μs only and limited by thermal development.

4. Resulting challenges for the designer

Combining the two areas for Reverse Biased Safe Operation and Short Circuit Safe Operation into a single diagram reveals a gap between them, as pictured in Figure 6.

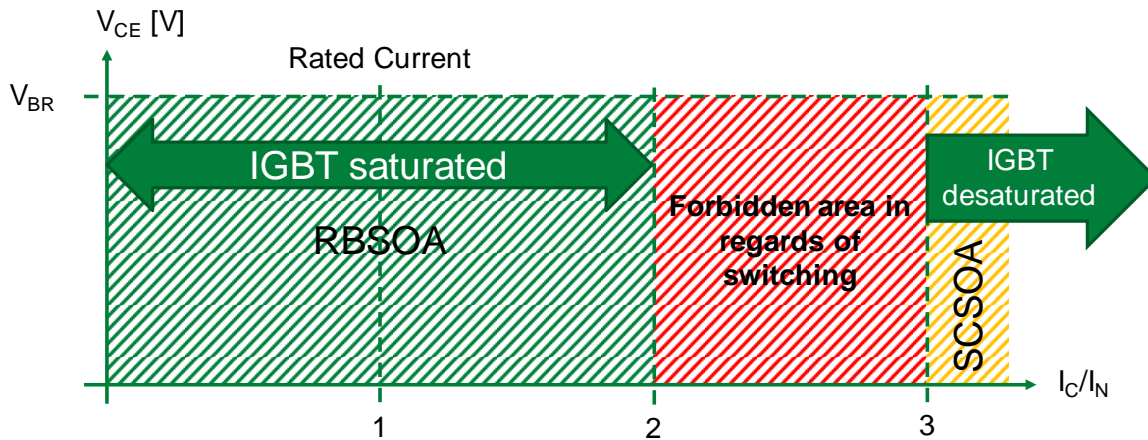


Figure 6. RBSOA, SCSOA, and the undefined region in between

Within the gap marked as forbidden area, located between twice and three times rated current, turning off the device is not allowed as it may lead to its destruction. The root cause of the destruction is found in very high local current densities, transiently forming during switching. The thermal limits in that case are reached already and additional burden due to switching losses leads to exceeding the limits. In turn, single cells on the chip fail and create a connection between collector and emitter. The current can no longer be turned off and the damage grows.

To overcome this situation, techniques to ensure that the IGBT reaches desaturation mode and enters the SCSOA can be used. The simplest way is to wait, instead of reacting on an overcurrent too quickly. Implementing a certain dead-time and fully exploit the 10 μs that the IGBT can withstand the conditions is a valid approach.

Further methods include the so-called 2-Level turn-off. The device is not turned off by immediately cancelling or even reversing the gate-emitter voltage. Instead, the gate-emitter voltage is first reduced to minimize the number of charge carriers available for current transport. This speeds up reaching the desaturation stage. A few microseconds later, when desaturation is reached, the gate-emitter voltage is set to zero or reversed. The device is then safely turned off within the SCSOA-specification.

This fact becomes particularly important when handling overcurrent situations.

From a given setup, measurements from a destructive turn-off event seen in Figure 7 were analyzed:

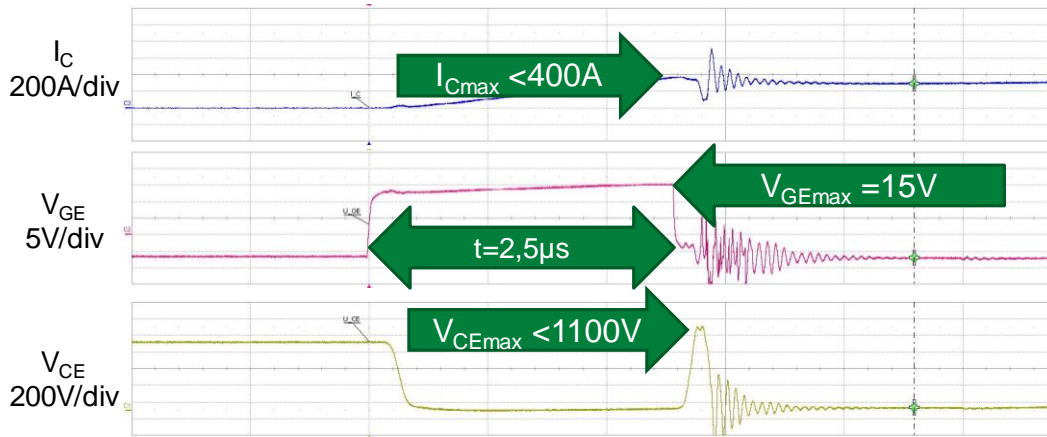


Figure 7. Measurement results from a destructive turn-off event

As the measurement reveals, the current turned off was well below the 450 A short-circuit limit. The gate-emitter-voltage was well-controlled, the time it took to turn off was below the 10 µs-limit and the overvoltage spike did not exceed the 1200 V the device is rated for. Still, the IGBT was destroyed, and the question raised, why so?

Entering the point of the turn-off into the diagram in Figure 6, the violation that happens becomes obvious in Figure 8:

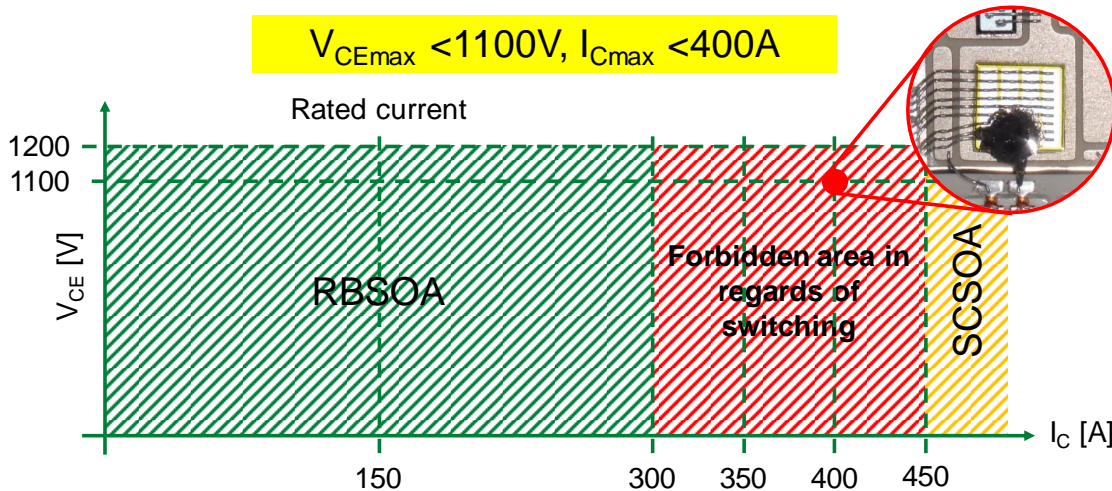


Figure 8. Locating the point of turn-off

Clearly, the switching event was done within the no-go-area with the destructive effect previously predicted.

To clear the situation, the control strategy for short circuit was changed. Instead of reacting on the overcurrent signal instantly and turn off after just 2.5 μs , a blanking time of about 6 μs was added.

Figure 9 represents the measurement done in the same setup.

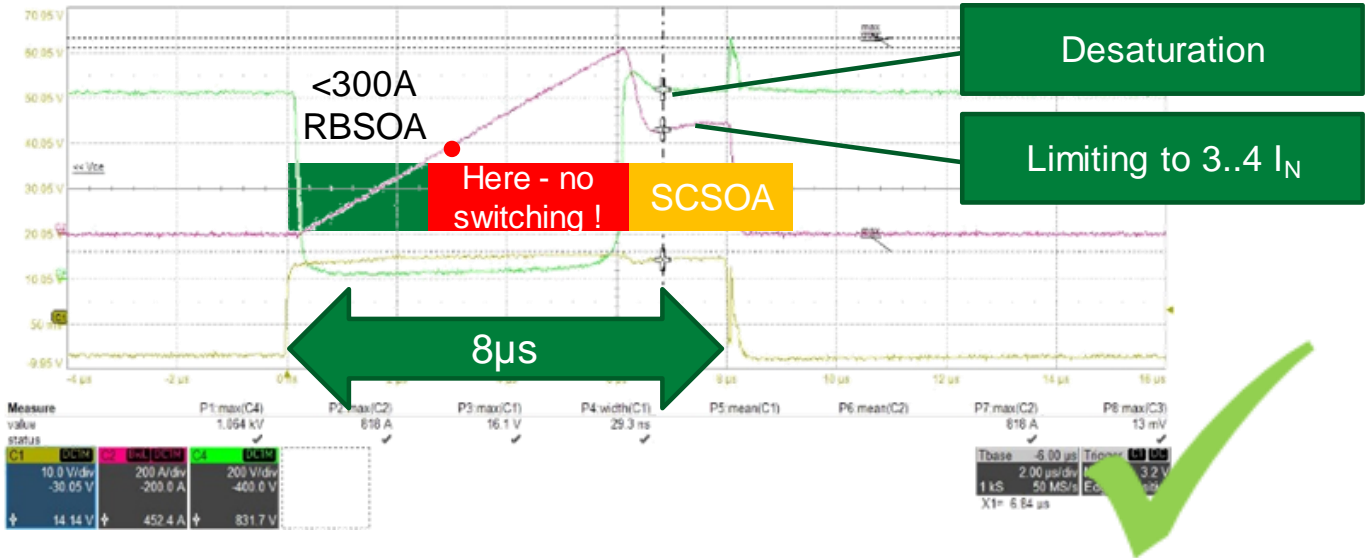


Figure 9. Properly turned off overcurrent or short-circuit event

While the red dot marks the former turn-off point, the current is now allowed to grow further. At first sight, this seems to worsen the situation as the losses and, as such, the chip temperature grows. However, after about 6 μs the IGBT reaches desaturation, enters the SCSOA and the turn-off after 8 μs is safely done without damaging the component.

MOSFETs, other than IGBTs, don't feature a dedicated SCSOA. At high currents, the MOSFET goes into linear operation as depicted in the FBSOA-diagram, so short-circuit and overcurrent events are covered by diagrams as given in Figure 2.

5. Conclusion

Handling overcurrent events, especially short circuit events, is challenging but manageable. Doing so while remaining within the given specifications can successfully be achieved.

Simply turning off a detected overcurrent as fast as possible may not be the best strategy as it may lead to damage caused by so-called RBSOA-exceedance. Ensuring that the IGBT reaches desaturation is a key factor in handling short circuit events with this technology.

For additional information please visit www.Littelfuse.com/powersemi

Disclaimer Notice - This document is provided by Littelfuse, Inc. ("Littelfuse") for informational and guideline purposes only. Littelfuse assumes no liability for errors or omissions in this document or for any of the information contained herein. Information is provided on an "as is" and "with all faults" basis for evaluation purposes only. Applications described are for illustrative purposes only and Littelfuse makes no representation that such applications will be suitable for the customer's specific use without further testing or modification. Littelfuse expressly disclaims all warranties, whether express, implied or statutory, including but not limited to the implied warranties of merchantability and fitness for a particular purpose, and non-infringement. It is the customer's sole responsibility to determine suitability for a particular system or use based on their own performance criteria, conditions, specific application, compatibility with other components, and environmental conditions. Customers must independently provide appropriate design and operating safeguards to minimize any risks associated with their applications and products.

Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, automotive, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly forth in applicable Littelfuse product documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation.

Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics



Expertise Applied | Answers Delivered

8755 W. Higgins Road
Suite 500
Chicago, IL 60631

www.littelfuse.com

CERTIFICATE OF COMPLIANCE

Restriction of Hazardous Substances (RoHS)

Product Series/ Part Number	Exemption/s Used
IXGA20N250HV	7a

This is to certify that product series/ part number listed above:

- Do not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB), or polybrominated diphenyl ethers (PBDE) above the indicated thresholds set forth in RoHS 2 Directive 2011/65/EU except when an applicable and valid EU RoHS exemption stipulated in the Annex III of the directive is specified. And,
- Do not contain Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP) above the indicated thresholds set forth in Directive (EU) 2015/863.

This certification does not modify or alter the terms of any contract or purchase agreement that exists between Littelfuse, Inc. and the purchaser of said parts. Further, I certify that I am authorized to make the representations provided in this compliance certification on behalf of my company.

Issued by:

Jennilyn Dinglasan-Santos

Manager 1, PEC

Global PEC

Email: JDinglasan@Littelfuse.com

Date: June 20, 2024

This information represents actual knowledge based on the information provided by our component and/or raw material suppliers.

If you require further information, feel free to contact us via email at envrequests@littelfuse.com